Abstracts

Advantages of flip chip technology in millimeter-wave packaging

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Power leakage into surface waves in monolithically integrated millimeter-wave circuits is to a great extent determined by the applied packaging technology. In this presentation it is shown that properly designed flip chip packages will not suffer from surface wave leakage. Coplanar waveguides on GaAs substrates are used to demonstrate the decisive differences in the leakage behavior of flip chip mounted MMICs and more conventional MMW packages, featuring surface mounted MMICs connected by wire bonds. All results are based on full wave spectral domain analysis and measurement data in the frequency range from 10 to 120 GHz.

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